



STM32F101xC/D/E and STM32F103xC/D/E Errata sheet

STM32F101xC/D/E and STM32F103xC/D/E revision Z high-density device limitations

Silicon identification

This errata sheet applies to the revision Z of the STMicroelectronics STM32F101xC/D/E access line and STM32F103xC/D/E performance line high-density products. These families feature an ARM™ 32-bit Cortex®-M3 core, for which an errata notice is also available (see [Section 1](#) for details).

The full list of root part numbers is shown in [Table 2](#). The products are identifiable as shown in [Table 1](#):

- by the Revision code marked below the order code on the device package
- by the last three digits of the Internal order code printed on the box label

Table 1. Device Identification⁽¹⁾

Order code	Revision code ⁽²⁾ marked on device
STM32F103xC, STM32F103xD, STM32F103xE	“Z”
STM32F101xC, STM32F101xD, STM32F101xE	“Z”

1. The REV_ID bits in the DBGMCU_IDCODE register show the revision code of the device (see the STM32F10xxx reference manual for details on how to find the revision code).
2. Refer to [Appendix A: Revision code on device marking](#) for details on how to identify the Revision code on the different packages.

Table 2. Device summary

Reference	Part number
STM32F101xCDE	STM32F101RC STM32F101VC STM32F101ZC
	STM32F101RD STM32F101VD STM32F101ZD
	STM32F101RE STM32F101VE STM32F101ZE
STM32F103xCDE	STM32F103RC STM32F103VC STM32F103ZC
	STM32F103RD STM32F103VD STM32F103ZD
	STM32F103RE STM32F103VE STM32F103ZE

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1 ARM™ 32-bit Cortex®-M3 limitations

An errata notice of the STM32F10xxx core is available from the following web address:

<http://infocenter.arm.com/help/index.jsp?topic=/com.arm.doc.eat0420a/>.

The direct link to the errata notice pdf is:

<http://infocenter.arm.com/help/topic/com.arm.doc.eat0420a/Cortex-M3-Errata-r1p1-v0.2.pdf>.

All the described limitations are minor and related to the revision r1p1-01rel0 of the Cortex-M3 core. [Table 3](#) summarizes these limitations and their implications on the behavior of high-density STM32F10xxx devices.

Table 3. Cortex-M3 core limitations and impact on microcontroller behavior

ARM ID	ARM category	ARM summary of errata	Impact on high-density STM32F10xxx devices
602117	Cat 2	LDRD with base in list may result in incorrect base register when interrupted or faulted	Minor
563915	Cat 2	Event register is not set by interrupts and debug	Minor
531064	impl	SWJ-DP missing POR reset sync	No
511864	Cat 3	Cortex-M3 may fetch instructions using incorrect privilege on return from an exception	No
532314	Cat 3	DWT CPI counter increments during sleep	No
538714	Cat 3	Cortex-M3 TPIU clock domain crossing	No
548721	Cat 3	Internal write buffer could be active whilst asleep	No
463763	Cat 3	BKPT in debug monitor mode can cause DFSR mismatch	Minor
463764	Cat 3	Core may freeze for SLEEPONEXIT single instruction ISR	Minor
463769	Cat 3	Unaligned MPU fault during a write may cause the wrong data to be written to a successful first access	No

1.1 Cortex-M3 limitations description for STM32F10xxx high-density devices

Only the limitations described below have an impact, even though minor, on the implementation of STM32F10xxx high-density devices.

All the other limitations described in the ARM errata notice (and summarized in [Table 3](#) above) have no impact and are not related to the implementation of STM32F10xxx high-density devices (Cortex-M3 r1p1-01rel0).

1.1.1 Cortex-M3 LDRD with base in list may result in incorrect base register when interrupted or faulted

Description

The Cortex-M3 Core has a limitation when executing an LDRD instruction from the system-bus area, with the base register in a list of the form LDRD Ra, Rb, [Ra, #imm]. The execution may not complete after loading the first destination register due to an interrupt before the second loading completes or due to the second loading getting a bus fault.

Workarounds

1. This limitation does not impact the STM32F10xxx code execution when executing from the embedded Flash memory, which is the standard use of the microcontroller.
2. Use the latest compiler releases. As of today, they no longer generate this particular sequence. Moreover, a scanning tool is provided to detect this sequence on previous releases (refer to your preferred compiler provider).

1.1.2 Cortex-M3 event register is not set by interrupts and debug

Description

When interrupts related to a WFE occur before the WFE is executed, the event register used for WFE wakeup events is not set and the event is missed. Therefore, when the WFE is executed, the core does not wake up from WFE if no other event or interrupt occur.

Workaround

Use STM32F10xxx external events instead of interrupts to wake up the core from WFE by configuring an external or internal EXTI line in event mode.

1.1.3 Cortex-M3 BKPT in debug monitor mode can cause DFSR mismatch

Description

A BKPT may be executed in debug monitor mode. This causes the debug monitor handler to be run. However, the bit 1 in the Debug fault status register (DFSR) at address 0xE00ED30 is not set to indicate that it was originated by a BKPT instruction. This only occurs if an interrupt other than the debug monitor is already being processed just before the BKPT is executed.

Workaround

If the DFSR register does not have any bit set when the debug monitor is entered, this means that we must be in this “corner case” and so, that a BKPT instruction was executed in debug monitor mode.

1.1.4 Cortex-M3 may freeze for SLEEPONEXIT single instruction ISR

Description

If the Cortex-M3 SLEEPONEXIT functionality is used and the concerned interrupt service routine (ISR) contains only a single instruction, the core becomes frozen. This freezing may occur if only one interrupt is active and it is preempted by an interrupt whose handler only contains a single instruction.

However, any new interrupt that causes a preemption would cause the core to become unfrozen and behave correctly again.

Workaround

This scenario does not happen in real application systems since all enabled ISRs should at least contain one instruction. Therefore, if an empty ISR is used, then insert an NOP or any other instruction before the exit instruction (BX or BLX).

2 STM32F10xxx silicon limitations

Table 4 gives quick references to all documented limitations.

Table 4. Summary of silicon limitations

Links to silicon limitations	
	Section 2.1: Voltage glitch on ADC input 0
	Section 2.2: Flash memory read after WFI/WFE instruction
	Section 2.3: Debug registers cannot be read by user software
Section 2.4: Alternate function	Section 2.4.1: USART1_RTS and CAN_TX
	Section 2.4.2: SPI1 in slave mode and USART2 in synchronous mode
	Section 2.4.3: SPI1 in master mode and USART2 in synchronous mode
	Section 2.4.4: SPI2 in slave mode and USART3 in synchronous mode
	Section 2.4.5: SPI2 in master mode and USART3 in synchronous mode
	Section 2.4.6: SDIO with TIM8
	Section 2.4.7: SDIO and TIM3_REMAP
	Section 2.4.8: SDIO with USART3 remapped and UART4
	Section 2.4.9: FSMC with I2C1 and TIM4_CH2
	Section 2.4.10: FSMC with USART2 remapped
	Section 2.4.11: FSMC with USART3 and TIM1 remapped
	Section 2.4.12: I2S2 in master/slave mode and USART3 in synchronous mode
	Section 2.4.13: USARTx_TX pin usage
	Section 2.5: PVD and USB wakeup events
	Section 2.6: SPI3 in I²S slave mode: timing sensitivity between I2S3_WS and I2S3_CK
	Section 2.7: Boundary scan TAP: wrong pattern sent out after the "capture IR" state
	Section 2.8: Flash memory BSY bit delay versus STRT bit setting
Section 2.9: I ² C peripheral	Section 2.9.1: Some software events must be managed before the current byte is being transferred
	Section 2.9.2: SMBus standard not fully supported
	Section 2.9.3: Start cannot be generated after a misplaced Stop
	Section 2.9.4: Mismatch on the "Setup time for a repeated Start condition" timing parameter
	Section 2.9.5: Data valid time ($t_{VD;DAT}$) violated without the OVR flag being set
Section 2.10: SPI peripheral	Section 2.10.1: CRC still sensitive to communication clock when SPI is in slave mode even with NSS high

Table 4. Summary of silicon limitations (continued)

Links to silicon limitations	
<i>Section 2.11: General-purpose timers</i>	<i>Section 2.11.1: Missing capture flag</i>
	<i>Section 2.11.2: Overcapture detected too early</i>
	<i>Section 2.11.3: General-purpose timer: regulation for 100% PWM</i>
<i>Section 2.12: LSI clock stabilization time</i>	
<i>Section 2.13: Multimaster access on the FSMC memory map</i>	
<i>Section 2.14: Limited multibyte support with SDIO cards</i>	
<i>Section 2.15: Parasitic TXE generation in SPI2/I2S2 slave mode + 16-bit data frame mode</i>	
<i>Section 2.16: USB packet buffer memory: over/underrun or COUNTn_RX[9:0] field reporting incorrect number if APB1 frequency is below 13 MHz</i>	

2.1 Voltage glitch on ADC input 0

Description

A low-amplitude voltage glitch may be generated (on ADC input 0) on the PA0 pin, when the ADC is converting with injection trigger. It is generated by internal coupling and synchronized to the beginning and the end of the injection sequence, whatever the channel(s) to be converted.

The glitch amplitude is less than 150 mV with a typical duration of 10 ns (measured with the I/O configured as high-impedance input and left unconnected). If PA0 is used as a digital output, this has no influence on the signal. If PA0 is used as a digital input, it will not be detected as a spurious transition, providing that PA0 is driven with an impedance lower than 5 k Ω . This glitch does not have any influence on the remaining port A pin or on the ADC conversion injection results, in single ADC configuration.

When using the ADC in dual mode with injection trigger, and in order to avoid any side effect, it is advised to distribute the analog channels so that Channel 0 is configured as an injected channel.

Workaround

None.

2.2 Flash memory read after WFI/WFE instruction

Conditions

- Flash prefetch on
- Flash memory timing set to 2 wait states
- FLITF clock stopped in Sleep mode

Description

If a WFI/WFE instruction is executed during a Flash memory access and the Sleep duration is very short (less than 2 clock cycles), the instruction fetch from the Flash memory may be corrupted on the next wakeup event.

Workaround

When using the Flash memory with two wait states and prefetch on, the FLITF clock must *not* be stopped during the Sleep mode – the FLITFEN bit in the RCC_AHBENR register must be set (keep the reset value).

2.3 Debug registers cannot be read by user software

Description

The DBGMCU_IDCODE and DBGMCU_CR debug registers are accessible only in debug mode (not accessible by the user software). When these registers are read in user mode, the returned value is 0x00.

Workaround

None.

2.4 Alternate function

In some specific cases, a potential weakness may exist between alternate function outputs mapped onto the same pin. On those IOs the EVENTOUT Cortex output feature cannot be used at the same time as another alternate function.

2.4.1 USART1_RTS and CAN_TX**Conditions**

- USART1 is clocked
- CAN is not clocked
- I/O port pin PA12 is configured as an alternate function output.

Description

Even if CAN_TX is not used, this signal is set by default to 1 if I/O port pin PA12 is configured as an alternate function output.

In this case USART1_RTS cannot be used.

Workaround

When USART1_RTS is used, the CAN must be remapped to either another IO configuration when the CAN is used, or to the unused configuration (CAN_REMAP[1:0] set to "01") when the CAN is not used.

2.4.2 SPI1 in slave mode and USART2 in synchronous mode**Conditions**

- SPI1 and USART2 are clocked
- I/O port pin PA4 is configured as an alternate function output.

Description

USART2 cannot be used in synchronous mode (USART2_CK signal), if SPI1 is used in slave mode.

Workaround

None.

2.4.3 SPI1 in master mode and USART2 in synchronous mode**Conditions**

- SPI1 and USART2 are clocked
- I/O port pin PA4 is configured as an alternate function output.

Description

USART2 cannot be used in synchronous mode (USART2_CK signal) if SPI1 is used in master mode and SP1_NSS is configured in software mode. In this case USART2_CK is not output on the pin.

Workaround

In order to output USART2_CK, the SSOE bit in the SPI1_CR2 register must be set to configure the pin in output mode.

2.4.4 SPI2 in slave mode and USART3 in synchronous mode**Conditions**

- SPI2 and USART3 are clocked
- I/O port pin PB12 is configured as an alternate function output.

Description

USART3 cannot be used in synchronous mode (USART3_CK signal) if SPI2 is used in slave mode.

Workaround

None.

2.4.5 SPI2 in master mode and USART3 in synchronous mode**Conditions**

- SPI2 and USART3 are clocked
- I/O port pin PB12 is configured as an alternate function output.

Description

USART3 cannot be used in synchronous mode (USART3_CK signal) if SPI2 is used in master mode and SP2_NSS is configured in software mode. In this case USART3_CK is not output on the pin.

Workaround

In order to output USART3_CK, the SSOE bit in the SPI2_CR2 register must be set to configure the pin in output mode,

2.4.6 SDIO with TIM8**Description**

Conflicts occur when:

- the SDIO is configured in 1- or 4-bit mode and TIM8_CH4 is configured as an output

The signals that conflict are the following:

- TIM8_CH4 and SDIO_D1

Workaround

Do not use TIM8_CH4 as an output when the SDIO is being used.

2.4.7 SDIO and TIM3_REMAP**Description**

When SDIO is configured in 1- or 4-bit mode, and TIM3 channels are remapped to PC6 to PC9, and configured as outputs, a conflict occurs between:

- TIM3_CH4 and SDIO_D1

Workaround

Do not use TIM3_CH4 as an output when the SDIO is being used.

2.4.8 SDIO with USART3 remapped and UART4**Description**

When SDIO is configured in 1-bit mode, there are conflicts with the USART3_TX pin remapped and with the UART4_TX pin. Conflicts are between the following signals:

- USART3_TX and SDIO_D2
- UART4_TX and SDIO_D2

Workaround

Use USART3_TX either in the default configuration (on the PB10 I/O) or remap USART3_TX to PD8 when the SDIO is being used.

Do not use UART4_TX when the SDIO is being used.

2.4.9 FSMC with I2C1 and TIM4_CH2**Description**

When the FSMC is being used, the NADV signal is set to 1 by default when the alternate function output is selected for this pin. TIM4_CH2 and the I2C1 SDA signal are in conflict with the NADV signal.

Workaround

Do not use TIM4_CH2 as an output when the FSMC is being used.

Concerning I2C1, it is possible to use the remap functionality available on the PB8 and PB9 pins.

2.4.10 FSMC with USART2 remapped

Description

When the FSMC is being used and the alternate function output is selected on PD4, PD5 and PD7, the following signals are in conflict:

- USART2_RTS remapped to PD4 and FSMC_OEN
- USART2_TX remapped to PD5 and FSMC_WEN
- USART2_CK remapped to PD7 and FSMC_NE1/FSMC_NCE2

Workaround

Use the USART2 default configuration (no remap).

2.4.11 FSMC with USART3 and TIM1 remapped

Description

When the FSMC is being used in 8-bit mode and the alternate function output is selected on the unused FSMC data lines 8 to 15, the following signals are in conflict:

- USART3_TX and USART3_CK remapped to PD8 and PD10, respectively, are in conflict with FSMC_D13 and FSMC_D15, respectively.
- TIM1_CH2, TIM1_CH3N, TIM1_CH3 and TIM1_CH4 used as outputs and remapped to PE11 to PE14, respectively, are in conflict with FSMC_D8 to FSMC_D11, respectively.

Workaround

- Use the USART3's partial remap functionality or default configuration (no remap).
- Do not use TIM1_CH2, TIM1_CH3N, TIM1_CH3 and TIM1_CH4 as outputs when they are remapped to PE11 to PE14, respectively.

2.4.12 I2S2 in master/slave mode and USART3 in synchronous mode

Conditions

- USART3 in synchronous mode is clocked
- I2S2 is not clocked
- I/O port pin PB12 is configured as an alternate function output

Description

If I2S2 was used prior to operating USART3 in synchronous mode, a conflict occurs between the I2S2_WS and USART3_CK signal even though the I2S2 clock was disabled.

Workaround

To use USART3 in synchronous mode, first disable the I2S2 clock, then perform a software reset of SPI2(I2S2).

2.4.13 USARTx_TX pin usage

Description

In USART receive-mode-only communication (TE = 0 in the USARTx_CR1 register), even when the USARTx_TX pin is not being used, the corresponding I/O port pin cannot be used to output another alternate function (in this mode the USARTx_TX output is set to 1 and thus no other alternate function output can be used).

This limitation applies to all USARTx_TX pins that share another alternate function output.

Workaround

Do not use the corresponding I/O port of the USARTx_TX pin in alternate function output mode. Only the input mode can be used (TE bit in the USARTx_CR1 has to be cleared).

2.5 PVD and USB wakeup events

Description

PVD and USB Wakeup, which are internally linked to EXTI line16 and EXTI line18, respectively, cannot be used as event sources for the Cortex-M3 core. As a consequence, these signals cannot be used to exit the Sleep or the Stop mode (exit WFE).

Workaround

Use interrupt sources and the WFI instruction if the application must be woken up from the Sleep or the Stop mode by PVD or USB Wakeup.

2.6 SPI3 in I²S slave mode: timing sensitivity between I2S3_WS and I2S3_CK

Description

When SPI3 is configured in I²S slave audio modemode in I2S Philips or PCM modes, If the I2S3_WS signal arrives too early with respect to the active edge of I2S3_CK, a wrong communication starting too soon may result: then, depending on the clock polarity and the Audio mode selected, it is either shifted by one bit from start to end or, the first left and right data items are lost and the others, shifted.

Workaround

None. Use I2S3 in slave mode in the MSB/LSB justified mode only.

2.7 Boundary scan TAP: wrong pattern sent out after the “capture IR” state

Description

After the “capture IR” state of the boundary scan TAP, the two lower significant bits in the instruction register should be loaded with “01” for them to be shifted out whenever a next instruction is shifted in.

However, the boundary scan TAP shifts out the latest value loaded into the instruction register, which could be “00”, “01”, “10” or “11”.

Workaround

The data shifted out, after the capture IR state, in the boundary scan flow should therefore be ignored and the software should check not only the two least significant bits (XXX01) but all register bits (XXXXX).

2.8 Flash memory BSY bit delay versus STRT bit setting

Description

When the STRT bit in the Flash memory control register is set (to launch an erase operation), the BSY bit in the Flash memory status register goes high one cycle later.

Therefore, if the FLASH_SR register is read immediately after the FLASH_CR register is written (STRT bit set), the BSY bit is read as 0.

Workaround

Read the BSY bit at least one cycle after setting the STRT bit.

2.9 I²C peripheral

2.9.1 Some software events must be managed before the current byte is being transferred

Description

When the EV7, EV7_1, EV6_1, EV2, EV8, and EV3 events are not managed before the current byte is being transferred, problems may be encountered such as receiving an extra byte, reading the same data twice or missing data.

Workarounds

When it is not possible to manage the EV7, EV7_1, EV6_1, EV2, EV8, and EV3 events before the current byte transfer and before the acknowledge pulse when changing the ACK control bit, it is recommended to:

1. use the I²C with DMA in general, except when the Master is receiving a single byte
2. use I²C interrupts and boost their priorities to the highest one in the application to make them uninterruptible

2.9.2 SMBus standard not fully supported

Description

The I²C peripheral is not fully compliant with the SMBus v2.0 standard since It does not support the capability to NACK an invalid byte/command.

Workarounds

A higher-level mechanism should be used to verify that a write operation is being performed correctly at the target device, such as:

1. Using the SMBAL pin if supported by the host
2. the alert response address (ARA) protocol
3. the Host notify protocol

2.9.3 Start cannot be generated after a misplaced Stop

Description

If a master generates a misplaced Stop on the bus (bus error), the peripheral cannot generate a Start anymore.

Workaround

In the I²C standard, it is allowed to send a Stop only at the end of the full byte (8 bits + acknowledge), so this scenario is not allowed. Other derived protocols like CBUS allow it, but they are not supported by the I²C peripheral.

A software workaround consists in asserting the software reset using the SWRST bit in the I2C_CR1 control register.

2.9.4 Mismatch on the “Setup time for a repeated Start condition” timing parameter

Description

In case of a repeated Start, the “Setup time for a repeated Start condition” (named $T_{su;sta}$ in the I²C specification) can be slightly violated when the I²C operates in Master Standard mode at a frequency between 88 kHz and 100 kHz.

The issue can occur only in the following configuration:

- in Master mode
- in Standard mode at a frequency between 88 kHz and 100 kHz (no issue in Fast-mode)
- SCL rise time:
 - If the slave does not stretch the clock and the SCL rise time is more than 300 ns (if the SCL rise time is less than 300 ns the issue cannot occur)
 - If the slave stretches the clock

The setup time can be violated independently of the APB peripheral frequency.

Workaround

Reduce the frequency down to 88 kHz or use the I²C Fast-mode if supported by the slave.

2.9.5 Data valid time ($t_{VD;DAT}$) violated without the OVR flag being set

Description

The data valid time ($t_{VD;DAT}$, $t_{VD;ACK}$) described by the I²C standard can be violated (as well as the maximum data hold time of the current data ($t_{HD;DAT}$)) under the conditions described below. This violation cannot be detected because the OVR flag is not set (no transmit buffer underrun is detected).

This issue can occur only under the following conditions:

- in Slave transmit mode
- with clock stretching disabled (NOSTRETCH=1)
- if the software is late to write the DR data register, but not late enough to set the OVR flag (the data register is written before)

Workaround

If the master device allows it, use the clock stretching mechanism by programming the bit NOSTRETCH=0 in the I2C_CR1 register.

If the master device does not allow it, ensure that the software is fast enough when polling the TXE or ADDR flag to immediately write to the DR data register. For instance, use an interrupt on the TXE or ADDR flag and boost its priority to the higher level.

2.10 SPI peripheral

2.10.1 CRC still sensitive to communication clock when SPI is in slave mode even with NSS high

Description

When the SPI is configured in slave mode with the CRC feature enabled, the CRC is calculated even if the NSS pin deselects the SPI (high level applied on the NSS pin).

Workaround

The CRC has to be cleared on both Master and Slave sides between the slave deselection (high level on NSS) and the slave selection (low level on NSS), in order to resynchronize the Master and Slave for their respective CRC calculation.

To procedure to clear the CRC is the following:

1. disable the SPI (SPE = 0)
2. clear the CRCEN bit
3. set the CRCEN bit
4. enable the SPI (SPE = 1)

2.11 General-purpose timers

2.11.1 Missing capture flag

Description

In capture mode, when a capture occurs while the CCRx register is being read, the capture flag (CCxIF) may be cleared without the overcapture flag (CCxOF) being set. The new data are actually captured in the capture register.

Workaround

An external interrupt can be enabled on the capture I/O just before reading the capture register (in the capture interrupt), and disabled just after reading the captured data. A missed capture will be detected by the EXTI peripheral.

2.11.2 Overcapture detected too early

Description

In capture mode, the overcapture flag (CCxOF) can be set even though no data have been lost.

Conditions

If a capture occurs while the capture register is being read, an overcapture is detected even though the previously captured data are correctly read and the new data are correctly stored into the capture register.

The system is at the limit of an overcapture but no data are lost.

Workaround

None.

2.11.3 General-purpose timer: regulation for 100% PWM

Description

When the OCREF_CLR functionality is activated, the OCxREF signal becomes de-asserted (and consequently OCx is deasserted / OCxN is asserted) when a high level is applied on the OCREF_CLR signal. The PWM then restarts (output re-enabled) at the next counter overflow.

But if the PWM is configured at 100% (CCxR > ARR), then it does not restart and OCxREF remains de-asserted.

Workaround

None.

2.12 LSI clock stabilization time

Description

When the LSIRDY flag is set, the clock may still be out of the specified frequency range (f_{LSI} parameter, see LSI oscillator characteristics in the product datasheet).

Workaround

To have a fully stabilized clock in the specified range, a software temporization of 100 μ s should be added.

2.13 Multimaster access on the FSMC memory map

Description

When multimaster accesses are performed on the FSMC memory map (address space from 0x6000 0000 to 0xA000 0FFF), an error could be generated, leading to either a bus fault or a DMA transfer error.

A multimaster can be:

- DMA1 and DMA2
- DMA1 and CPU
- DMA2 and CPU

Workaround

If multimaster accesses are required on the FSMC address space, the software must ensure that accesses are performed one at a time, and not at the same time.

2.14 Limited multibyte support with SDIO cards

Description

The SDIO standard allows multibyte transfers (to transfer any number of data bytes from 1, 2, 3 up to 512), which extends the block transfer of the SD standard.

In a multibyte transfer operation, CMD53 will transfer only a number of bytes that is equal to a power of 2 (1, 2, 4, 8...512) between 1 and 512.

Workaround

In case the application needs to read a number of bytes N that is not a power of 2, and if the SDIO device supports the multiblock mode, it is then possible to read the N bytes using the CMD53 multiblock command:

- Configure the SDIO block size to 1 byte
- Read N bytes using the CMD53 multiblock command

2.15 Parasitic TXE generation in SPI2/I2S2 slave mode + 16-bit data frame mode

Description

When the SPI2/I2S2 slave mode is used either in transmit or in full-duplex mode, and the data frame format is configured to 16-bit, the TXE flag may go high two times before RXNE is set, that is, TXE may be asserted before the data already in the data register are transmitted. This may result in data loss during transmission.

Workarounds

1. In SPI mode, use the 8-bit data frame mode instead of the 16-bit mode.
2. The 16-bit mode may be used if the master stops the clock for every data transfer. The SPI2/I2S2 slave then has enough time to load the data register on the RXNE flag going high.

2.16 USB packet buffer memory: over/underrun or COUNTn_RX[9:0] field reporting incorrect number if APB1 frequency is below 13 MHz

Description

The USB peripheral's packet buffer memory is expected to operate at a minimum APB1 frequency of 8 MHz.

It may however happen that, when OUT transactions are sent by the Host with a data payload size exactly equal to the maximum packet size already programmed in the COUNTn_RX packet buffer memory (via the BLSIZE and NUM_BLOCK[4:0] fields), the packet and all bytes from the Host are correctly received and stored into the packet buffer memory, but, the COUNTn_RX[9:0] field indicates an incorrect number (one byte less).

Workaround

This limitation concerns applications that check the exact number of bytes received in the packet buffer memory. In order to avoid that these applications interpret a Host error and so, stall the OUT endpoint even if no data reception error actually occurred, it is recommended to:

1. increase the APB1 frequency to a minimum of 13 MHz, or
2. increase the APB1 frequency to a minimum of 10 MHz. Then program USB_COUNTn_RX (via the BLSIZE and NUM_BLOCK[4:0] fields) to have more than the number of bytes in the maximum packet size allocated for reception in the packet buffer memory

Appendix A Revision code on device marking

Figure 1, Figure 2, Figure 3, Figure 3, Figure 5 and Figure 6 show the marking compositions for the LFBGA144, LFBGA100, WLCSP64, LQFP144, LQFP100 and LQFP64 packages, respectively. The only fields shown are the Additional field containing the revision code and the Year and Week fields making up the date code.

Figure 1. LFBGA144 top package view

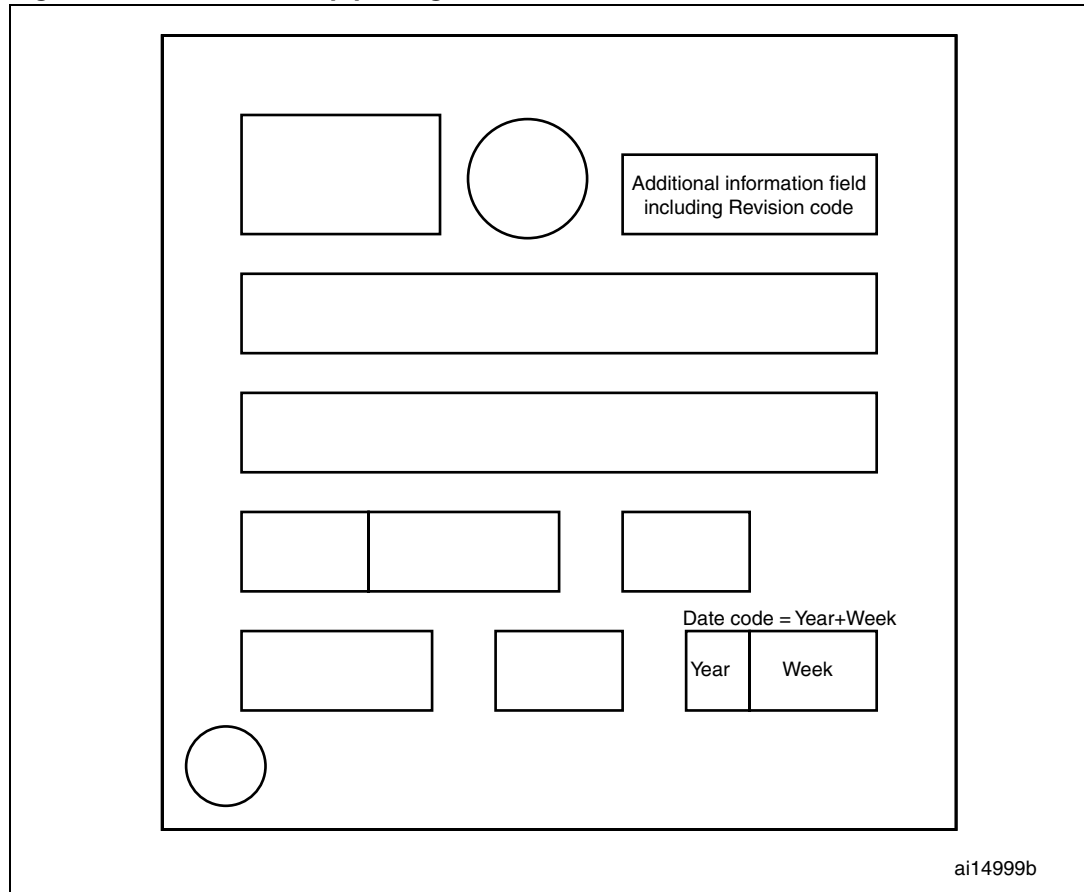


Figure 2. LFBGA100 top package view

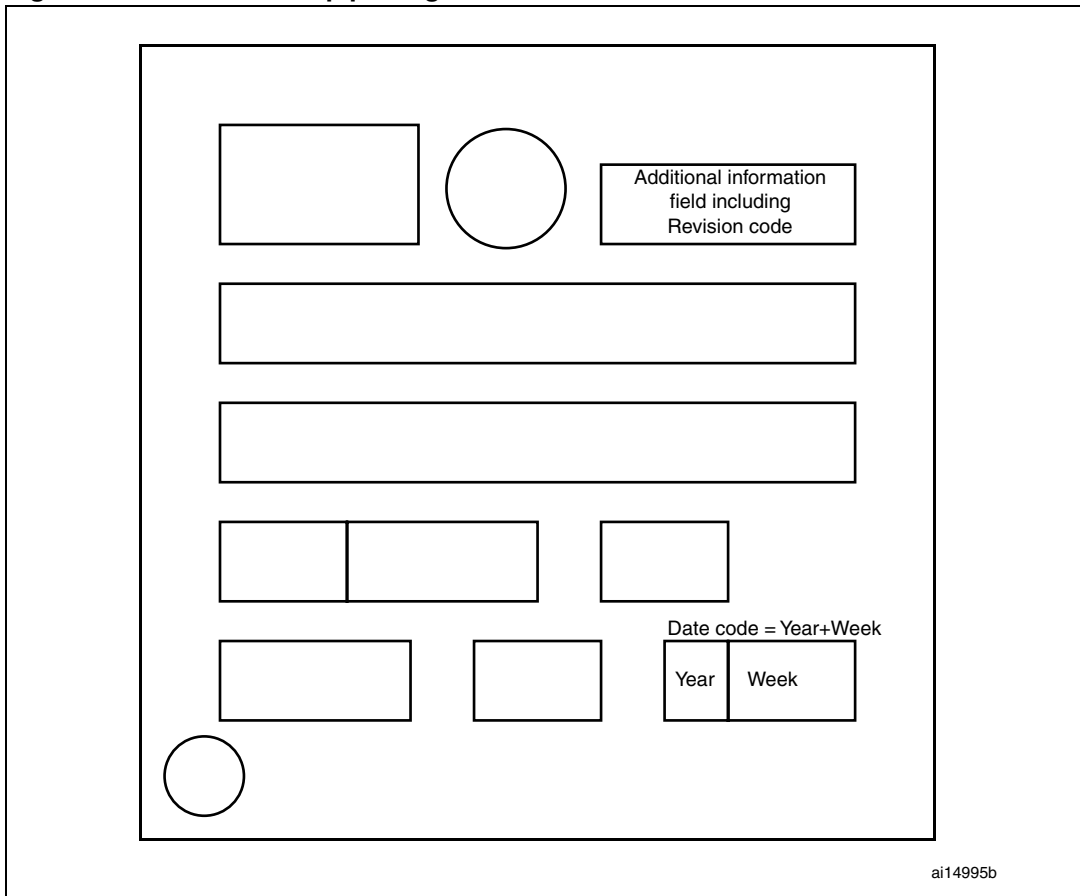


Figure 3. WLCSP64 top package view

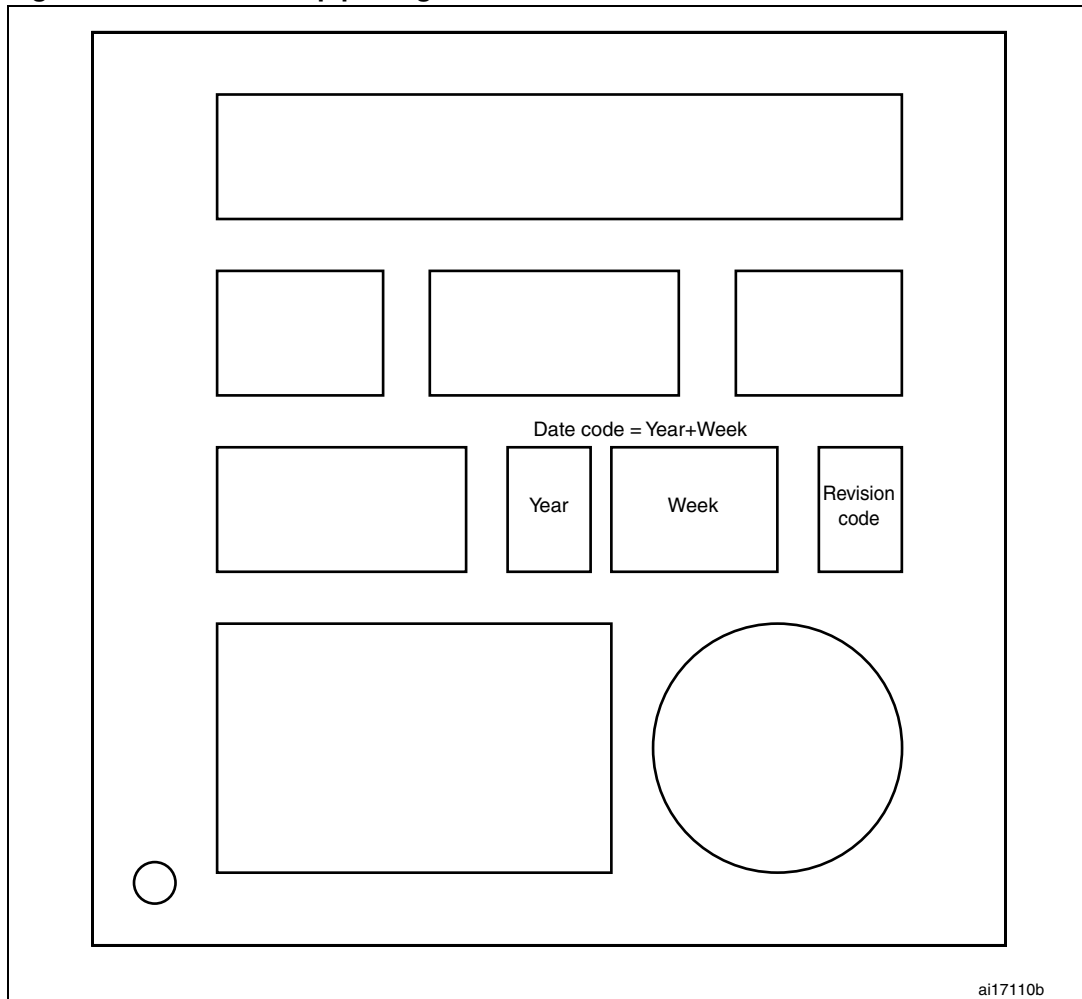


Figure 4. LQFP144 top package view

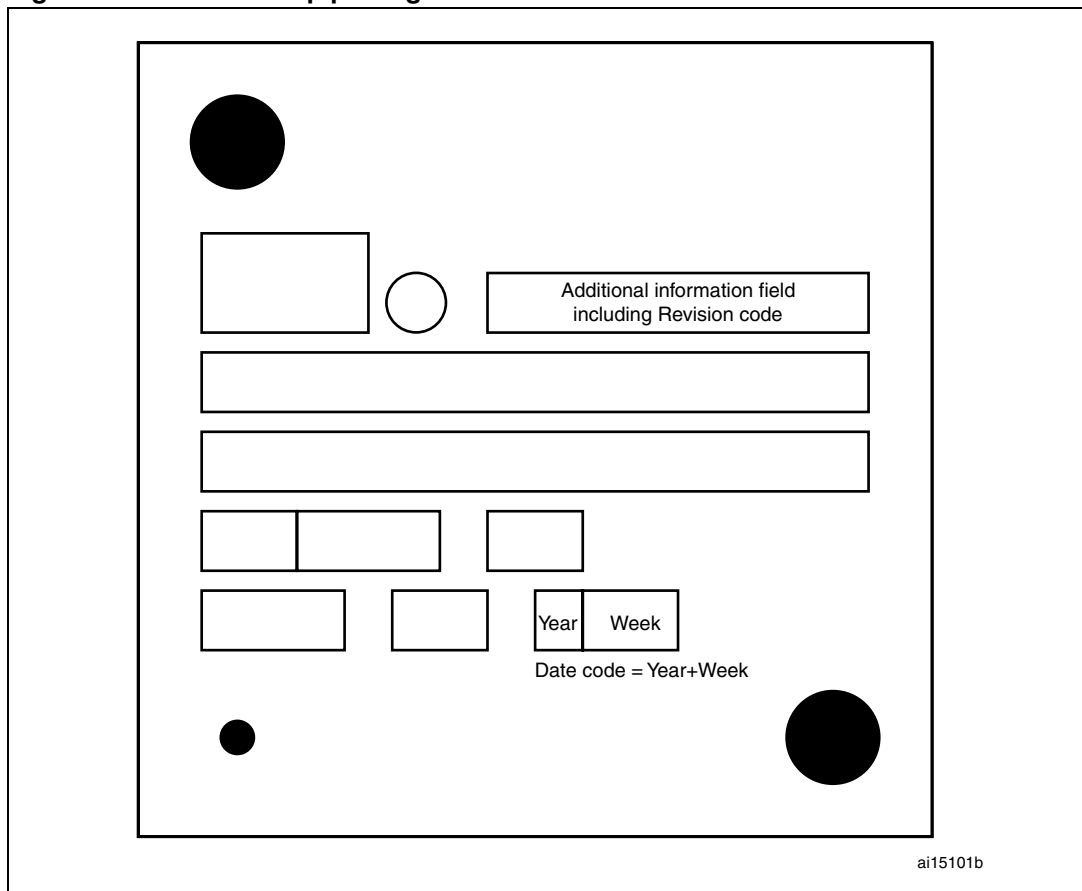
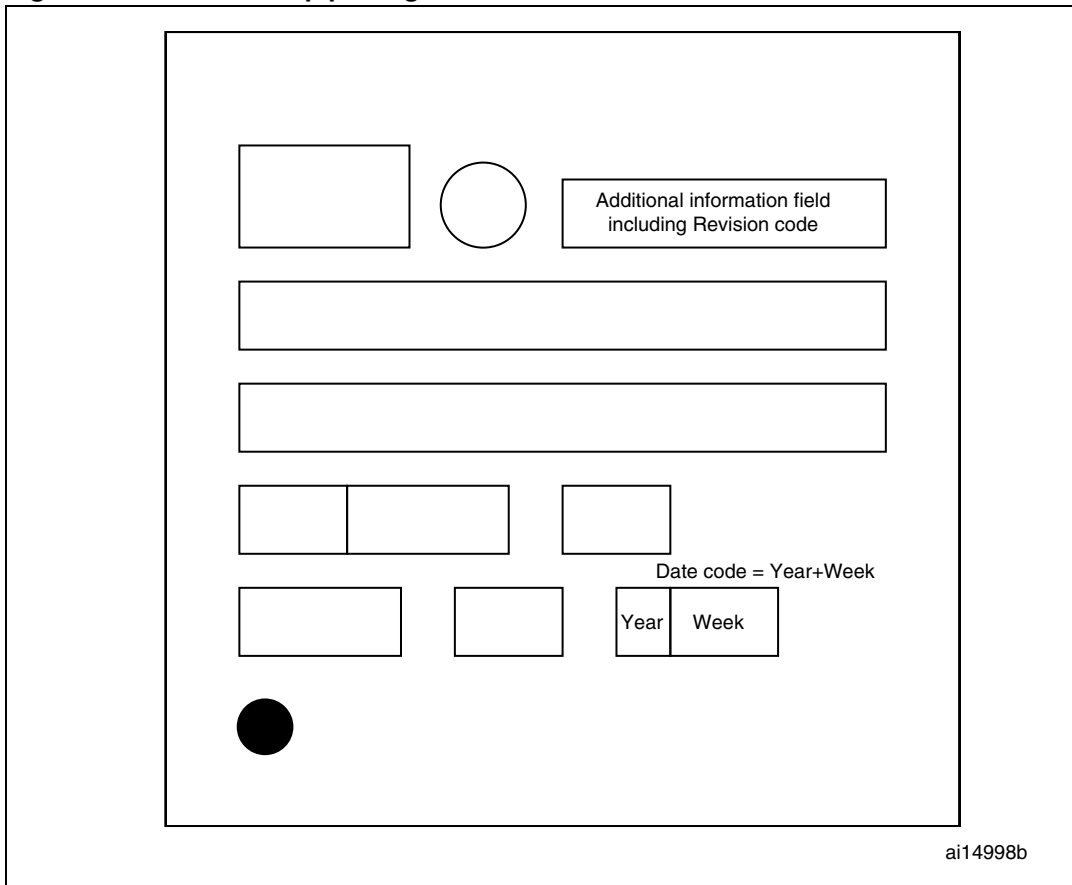
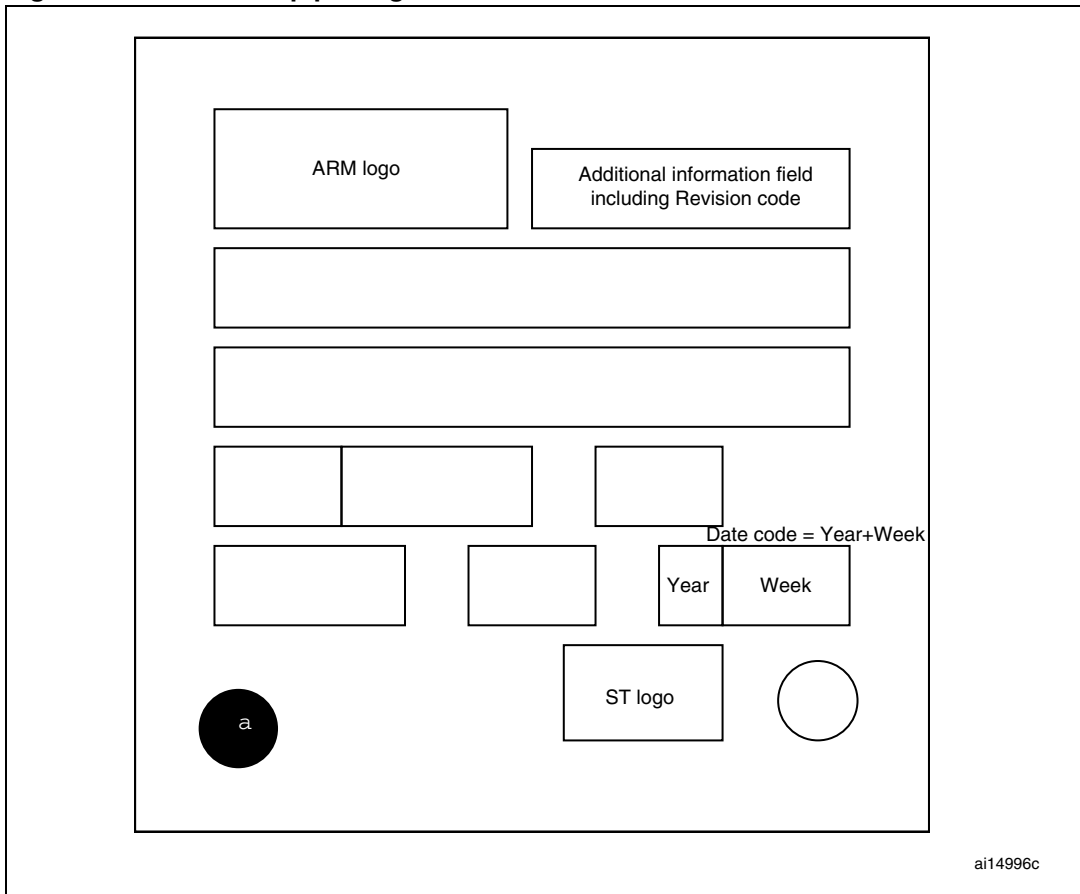


Figure 5. LQFP100 top package view



ai14998b

Figure 6. LQFP64 top package view



Revision history

Table 5. Document revision history

Date	Revision	Changes
23-May-2008	1	Initial release.
21-Jul-2008	2	Section 2.5: PVD and USB wakeup events added.
29-Sep-2008	3	Figure 6: LQFP64 top package view on page 28 corrected.
11-Feb-2009	4	<p>Section 1: ARM™ 32-bit Cortex®-M3 limitations specified (Table 3: Cortex-M3 core limitations and impact on microcontroller behavior added limitations described).</p> <p>Limitation added: SPI3 in I²S slave mode: timing sensitivity between I2S3_WS and I2S3_CK on page 16.</p> <p>Added limitations:</p> <ul style="list-style-type: none"> – Boundary scan TAP: wrong pattern sent out after the “capture IR” state – Flash memory BSY bit delay versus STRT bit setting – I²C peripheral – General-purpose timers – LSI clock stabilization time – Section 2.13: Multimaster access on the FSMC memory map – Section 2.14: Limited multibyte support with SDIO cards <p>Table 4: Summary of silicon limitations on page 9 added.</p>
22-Jun-2009	5	<p>Introduction text updated in Section 2.4: Alternate function.</p> <p>Section 2.4.10: FSMC with USART2 remapped updated.</p> <p>Section 2.4.11: FSMC with USART3 and TIM1 remapped added.</p> <p>Section 2.14: Limited multibyte support with SDIO cards clarified.</p> <p>Section 2.15: Parasitic TXE generation in SPI2/I2S2 slave mode + 16-bit data frame mode added.</p> <p>Figure 3: WLCSP64 top package view added.</p>
21-Jul-2009	6	Section 2.4.12: I2S2 in master/slave mode and USART3 in synchronous mode added.
11-Jan-2010	7	<p>Workaround modified in Section 2.6: SPI3 in I²S slave mode: timing sensitivity between I2S3_WS and I2S3_CK.</p> <p>Added limitations:</p> <ul style="list-style-type: none"> – Section 2.4.13: USARTx_TX pin usage – Section 2.9.3: Start cannot be generated after a misplaced Stop – Section 2.9.4: Mismatch on the “Setup time for a repeated Start condition” timing parameter – Section 2.9.5: Data valid time (t_{VD;DAT}) violated without the OVR flag being set – Section 2.10.1: CRC still sensitive to communication clock when SPI is in slave mode even with NSS high – Section 2.15: Parasitic TXE generation in SPI2/I2S2 slave mode + 16-bit data frame mode <p>Date code added to Figure 1 to Figure 6.</p>

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